FEB 2 7 2006

Atty. Docket No. PIA31224/DBE/US

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF:

:

Kyung Hee KOH

: GROUP ART UNIT: 2891

APPLICATION NO: 10/751,198

:

FILED: DECEMBER 30, 2003

: EXAMINER: WILSON, Christian D.

FOR: METHOD FOR PACKAGING A

MULTI-CHIP MODULE OF A SEMICONDUCTOR DEVICE

I hereby certify that this document is being facsimile transmitted to the USPTO or deposited with the United States Postal Service as first class mail in an envelope addressed to Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on February 27, 2006.

By: Jennie Heaton

AMENDMENT AND REQUEST FOR RECONSIDERATION UNDER 35 U.S.C. 132 AND 37 C.F.R. 1.116

Mail Stop RCE COMMISSIONER FOR PATENTS P.O. BOX 1450 ALEXANDRIA, VA 22313-1450

SIR:

Responsive to the Office Action dated October 26, 2005, Applicant respectfully requests reconsideration of the above-identified application in view of the following amendments and remarks.